

MATERIAL DECLARATION SHEET



Material Number	PSD220S Series			
Product Line	Fixed Resistors			
Compliance Date	2024/7/29			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Lead Plating	Tin Plating	1.32	Tin	7440-31-5	90.9	0.055	0.061
				Copper	7440-50-8	7.6	0.005	
				Silver	7440-22-4	1.5	0.001	
2	Leads	Copper	300	Copper	7440-50-8	100	13.785	13.785
3	Inside Soldering	Tin Plating	4.1	Tin	7440-31-5	7.3	0.014	0.189
				Lead	7439-92-1	85.4	0.161	
				Silver	7440-22-4	7.3	0.014	
4	Heatsink	Copper Plate	1350	Copper	7440-50-8	100	62.031	62.031
5	Heatsink Plating	Nickel Plating	1	Nickel	7440-02-0	100	0.046	0.046
6	Substrate	Ceramic	115.68	Alumina	1344-28-1	99.6	5.294	5.316
				Silicon Dioxide	7631-86-9	0.4	0.022	
7	Coating	Epoxy	0.13	Brominated Epoxy Oligomer	68928-70-1	100	0.006	0.006

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8	Resistor Material	Thickfilm	2.02	Silver	7440-22-4	21.4	0.02	0.094
				Platinum	7440-06-4	29.7	0.028	
				Lead Monoxid	1317-36-8	10.4	0.01	
				Silicon Dioxide	7631-86-9	15.6	0.015	
				Ruthnium Oxid	12036-10-1	10.4	0.01	
				Ruthnium Dioxid	12036-10-1	7	0.006	
				Lead Ruthenium Oxid	37194-88-0	5.5	0.005	
9	Cover	Silicone Based	2	Silicon	63148-62-9	100	0.092	0.092
10	Mold	Fortron 1140L4	400	Polyphenylensulfid	26125-40-6	100	18.38	18.38
			Total weight	2176.25				

This Document was updated on: 2024/7/29

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. Resistive material weight will be different based on the resistance value.
3. The weight of the core and coating material will differ based on the size.